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(54) POWER APPARATUS WITH **ELECTROMAGNETIC INTERFERENCE** REDUCTION FUNCTION

(71) Applicant: SENTEC E&E CO., LTD., TAOYUAN CITY (TW)

(72) Inventors: Jason HUANG, TAOYUAN CITY (TW); Liang-Yo CHEN, TAOYUAN CITY (TW); Pi-Sheng HSU, TAOYUAN CITY (TW); Chun-Ming WEI, TAOYUAN CITY (TW)

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ABSTRACT (57)

A power apparatus includes a substrate, a first power circuit, and a second power circuit. The substrate includes a first metallization region, a second metallization region, and a third metallization region which are separated from each other. The first power circuit is electrically connected to the first metallization region and the third metallization region, and is arranged across the second metallization region and fails to be in contact with the second metallization region. The second power circuit is electrically connected to the second metallization region and the third metallization region, and fails to be in contact with the first metallization

